



Patent Application Serial No. 10/813,789
Filed March 23, 2004

DECLARATION OF WEI GAO

I, Wei Gao, hereby declare as follows:

1. My residence address is 2402 SE 180th CT, Vancouver, WA, 98683
2. Since April 2001, I have been employed by Sharp Laboratories of America (SLA), Inc., 5700 N.W. Pacific Rim Boulevard, Camas, Washington 98607. My title is Member of Technical Staff. My responsibilities include R&D in process technologies.
3. I am a co-inventor of Patent Application Serial No. 10/813,789. With the full knowledge of my co-inventors Yoshi Ono and John Conley Jr, I hereby state and declare unequivocally that I, along with my co-inventors, invented the device recited in claims 1-20 prior to November 17, 2003.
4. Attachment D is a true copy of the SLA patent disclosure document filed with the SLA Patent Department. I affirm that the patent disclosure document was written, signed, and witnessed before November 17, 2003. The disclosure shows the concept of a microlens structure formed by patterning a hard mask formed over a transparent film, and etching the hard mask and transparent film to form a lens shape.
5. Attachment E is a true copy of a monthly report written by myself to co-inventor Yoshi Ono. The figures and descriptions in the report are very similar to both the disclosure and patent application. For example, Figs. 1-4 in the report are almost identical to the figures appearing on pages 7 and 8 of the disclosure, and Figs. 3-6 in the application. Fig. 7 in the monthly report, and its accompanying explanation, show and describe the

formation of a microlens, and are proof that the invention recited in claims 1-20 was reduced to practice. This monthly report was filed prior to November 17, 2003.

6. I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful, false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United State Code and that such willful, false statements may jeopardize the validity of the application or patent issuing thereon.

5/11/2006

Date



Wei Gao